



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application:
Rajeev Joshi et al.

Serial No.: 10/731,453

Filed: December 9, 2003

For: WAFER-LEVEL CHIP SCALE PACKAGE AND
METHOD FOR FABRICATING AND USING THE
SAME

Confirmation No. 4432

Group Art Unit: 2891

Examiner: Zarnecke, David A.

Mail Stop AF
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

AMENDMENT AND REQUEST FOR RECONSIDERATION
UNDER 37 C.F.R. §§ 1.111 & 1.115

In response to the Office Action mailed on June 12, 2006, Applicant requests reconsideration of this application in light of the following remarks.

Amendments to the Specification are reflected in the list of claims that begins on page 2 of this paper.

Remarks begin on page 3 of this paper.

I hereby certify that this correspondence is being deposited with the United States Postal Service as First Class Mail in an envelope addressed to:
Commissioner for Patents, Alexandria, VA 22313-1450, on this 10th day of
September 2006.

Signed: _____

9/6/2006